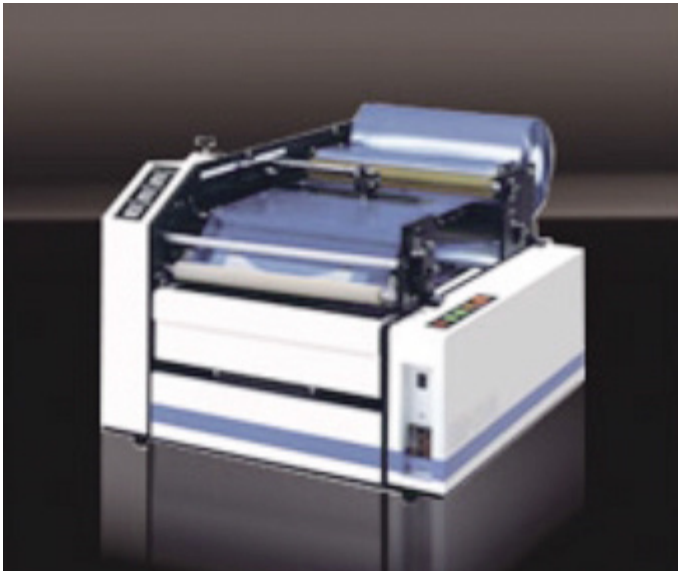


300mm Semi-Automatic Wafer Mounter

# RAD-2500m/12



## Outline

–Semi-automatic wafer mounter that mounts wafer onto the pre-cut dicing tape once the operator supplies the wafer and ring frame by hand.

**Options** ·Static Eliminator

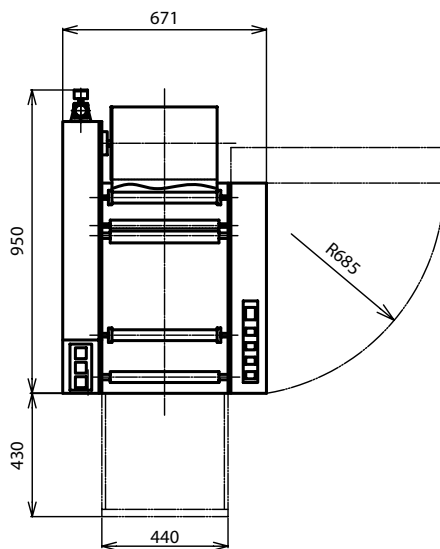
·Top Cover

·Wafer Positioning Pins

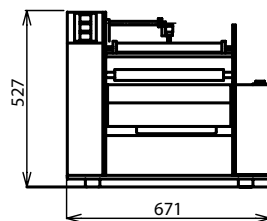
**Suitable Tapes** ·Pre-cut dicing tape : Adwill D series, G series

·Dicing die bonding tape : Adwill LE Tape

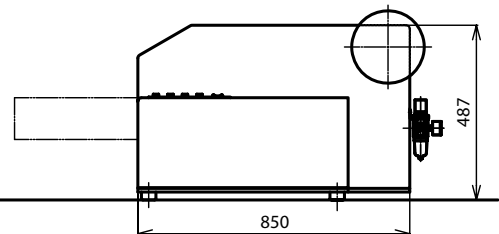
## External View



Top View



Front View



Right Side View

Unit:mm

## Facility

Power Supply	Voltage	: AC100V ( ±10%)
	Frequency	: 50/60Hz
	Phase	: single phase
	Power consumption	: 0.2kW
Air Supply	Air pressure	: 0.5-0.8MPa
	Air consumption	: >150L/min (ANR)

## Applicable Wafer Size

300mm

Additional compatibility with various wafer sizes and shapes are available as an option. Please feel free to inquire.

## Size

Width : 671mm

Depth : 950mm

(with table fully advanced : Max. 1,380mm)

Height : 527mm

## Weight

110kg

## Processing Capacity

22sec/wafer (excludes setting time)



**LINTEC Corporation** *Linking your dreams*

●Head Office:23-23 Honcho, Itabashi-ku, Tokyo 173-0001, Japan

Contact:Advanced Materials Operations8th Fl, Bunkyo Garden Gate Tower, 1-1-1 Koishikawa, Bunkyo-ku, Tokyo 112-0002, Japan  
TEL. +81-3-3868-7737 FAX. +81-3-3868-7726

<https://www.adwill-global.com/en>